

Abstract Submitted  
for the MAR14 Meeting of  
The American Physical Society

**Fabrication of Atomically Layered Material Heterostructures of WSe<sub>2</sub> and hBN**<sup>1</sup> YAFANG YANG, HUGH CHURCHILL, BRITT BAUGHER, JAVIER SANCHEZ-YAMAGISHI, PABLO JARILLO-HERRERO, Massachusetts Institute of Technology — We discuss fabrication methods for hBN-WSe<sub>2</sub>-hBN heterostructures designed to create high quality and high mobility monolayer WSe<sub>2</sub> devices by encapsulating the WSe<sub>2</sub> in a relatively clean and impurity-free environment. We use a release polymer to pick up hBN and WSe<sub>2</sub> from a SiO<sub>2</sub> substrate, and transfer the stack onto another pre-cleaned hBN flake. In this way the WSe<sub>2</sub> channel is protected from resist residue by hBN above and below, and thus stays pristine and clean. Various fabrication strategies will be discussed, including a comparison of MMA and PPC as release polymers. We characterize the performance of these devices with electrical transport measurements.

<sup>1</sup>We acknowledge support from ONR Young Investigator Award N00014-13-1-0610.

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Date submitted: 13 Nov 2013

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